

#### **NPN Silicon RF Transistor\***

- For low noise, high-gain broadband amplifiers at collector currents from 1 mA to 20 mA
- $f_T = 9$  GHz, F = 1 dB at 1 GHz
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101
- \* Short term description





### ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration			Package
BFR949L3	RK	1 = B	2 = E	3 = C	TSLP-3-1

### **Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$	10	V
Collector-emitter voltage	V <sub>CES</sub>	20	
Collector-base voltage	$V_{\mathrm{CBO}}$	20	
Emitter-base voltage	V <sub>EBO</sub>	1.5	
Collector current	I <sub>C</sub>	50	mA
Base current	I <sub>B</sub>	5	
Total power dissipation <sup>2)</sup>	P <sub>tot</sub>	250	mW
<i>T</i> <sub>S</sub> ≤ 101 °C			
Junction temperature	$T_{i}$	150	°C
Ambient temperature	T <sub>A</sub>	-65 150	
Storage temperature	$T_{ m stg}$	-65 150	

#### **Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>3)</sup>	$R_{thJS}$	≤ 195	K/W

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<sup>&</sup>lt;sup>1</sup>Pb-containing package may be available upon special request

 $<sup>^2</sup>T_{\mbox{\scriptsize S}}$  is measured on the collector lead at the soldering point to the pcb

 $<sup>^3</sup>$ For calculation of  $R_{\mathrm{thJA}}$  please refer to Application Note Thermal Resistance



**Electrical Characteristics** at  $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics				•	•
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	10	-	-	V
$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$	. ,				
Collector-emitter cutoff current	I <sub>CES</sub>	-	-	100	μΑ
$V_{CE} = 20 \text{ V}, \ V_{BE} = 0$					
Collector-base cutoff current	/ <sub>CBO</sub>	-	-	100	nA
$V_{\rm CB} = 10 \text{ V}, I_{\rm E} = 0$					
Emitter-base cutoff current	/ <sub>EBO</sub>	-	-	0.1	μΑ
$V_{\rm EB} = 1 \text{ V}, I_{\rm C} = 0$					
DC current gain-	h <sub>FE</sub>	100	140	180	-
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 6 V, pulse measured					



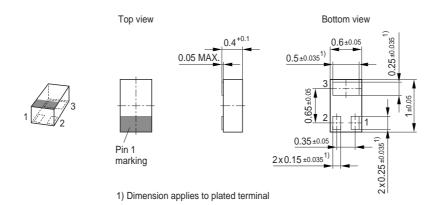
**Electrical Characteristics** at  $T_{\Delta} = 25^{\circ}\text{C}$ , unless otherwise specified

Parameter Parameter Stics at $I_A = 25$ °C, unle	Symbol		Values		
		min.	typ.	max.	
AC Characteristics (verified by random samp	oling)				
Transition frequency	$f_{T}$	7	9	-	GHz
$I_{\rm C}$ = 15 mA, $V_{\rm CE}$ = 6 V, $f$ = 1 GHz					
Collector-base capacitance	C <sub>cb</sub>	-	0.25	0.4	pF
$V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$ ,					
emitter grounded					
Collector emitter capacitance	C <sub>ce</sub>	-	0.15	-	
$V_{CE} = 10 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0,$					
base grounded					
Emitter-base capacitance	$C_{eb}$	-	0.7	-	
$V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{CB} = 0$ ,					
collector grounded					
Noise figure	F				dB
$I_{\rm C} = 5 \text{ mA}, \ V_{\rm CE} = 6 \text{ V}, \ Z_{\rm S} = Z_{\rm Sopt},$					
f = 1 GHz		-	1	2.5	
$I_{\text{C}} = 3 \text{ mA}, V_{\text{CE}} = 8 \text{ V}, Z_{\text{S}} = Z_{\text{Sopt}}$					
f = 1.8 GHz		-	1.3	-	
Power gain <sup>1)</sup>	G <sub>ms</sub>	-	21.5	-	-
$I_{\rm C} = 10 \text{ mA}, \ V_{\rm CE} = 8 \text{ V}, \ Z_{\rm S} = Z_{\rm Sopt} \ ,$					
$Z_{L} = Z_{Lopt}$ , $f = 900 \text{ MHz}$					
Power gain, maximum available <sup>1)</sup>	G <sub>ma</sub>	-	15.5	-	dB
$I_{\rm C} = 10 \text{ mA}, \ V_{\rm CE} = 8 \text{ V}, \ Z_{\rm S} = Z_{\rm Sopt} \ ,$					
$Z_{L} = Z_{Lopt}$ , $f = 1.8 \text{ GHz}$					
Transducer gain	S <sub>21e</sub>   <sup>2</sup>				dB
$I_{\rm C} = 15 \text{ mA}, \ V_{\rm CE} = 6 \text{ V}, \ Z_{\rm S} = Z_{\rm L} = 50\Omega \ ,$					
f = 1 GHz		14	17	-	
$I_{\rm C} = 10 \text{ mA}, \ V_{\rm CE} = 8 \text{ V}, \ Z_{\rm S} = Z_{\rm L} = 50\Omega \ ,$					
f = 1.8 GHz		-	12	_	

 $<sup>^{1}</sup>G_{\text{ma}} = |S_{21} / S_{12}| \text{ (k-(k^2-1)^{1/2})}, G_{\text{ms}} = |S_{21} / S_{12}|$ 

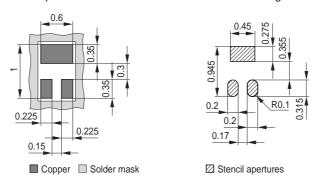


### Package Outline

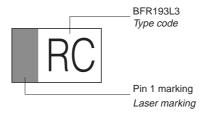


## Foot Print

For board assembly information please refer to Infineon website "Packages"

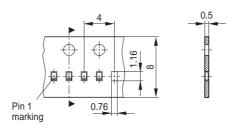


### Marking Layout (Example)



### Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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